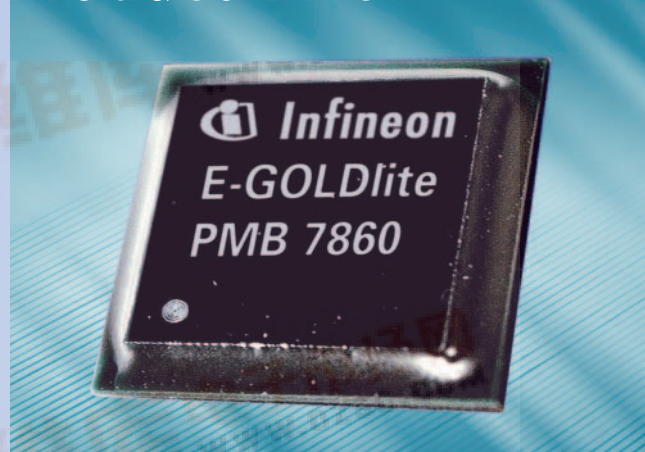


# PMB 7860

E-GOLDlite

Lowest Cost GSM/GPRS/Baseband IC



E-GOLDlite is a very cost optimised and compact integrated mixed signal baseband IC for complete GSM/GPRS modems. Its flexible systems architecture fits at best to future entry level phones with GPRS and basic MMS functionality. In conjunction with Infineon's single chip CMOS RF-transceiver SMARTi SD and the power management IC E-POWERlite the single chip IC E-GOLDlite reaches best-in-class system costs.

## Applications

- Future GSM/GPRS entry level phones with basic MMS functionality and cost optimised highly integrated modems and data modules

## Features

- Supports a wide variety of RF architectures
- 1.5 V design in 0.13  $\mu$  drawn C11-technology
- Microcontroller C166s CPU with 52 MHz
- DSP TEAKLite<sup>®</sup> with 104 MHz
- All Interfaces required for scalable systems (ASCs, I<sup>2</sup>Cs, I<sup>2</sup>Ss, ISSs)
- Voice memo and voice activity detection
- Echo cancellation for handsfree
- CSD up to 14.4 kbit/s, HSCD class 4
- GPRS CS1 to CS4, up to class 10
- Speech codecs HR, FR, EFR and AMR
- E-OTD and TTY support
- Integrated Polyringer

## Package

- Highest integration with Flip Chip package LF2BGA-201
- Smallest board footprint of 8x8 mm

## Documentation/ Development and Support

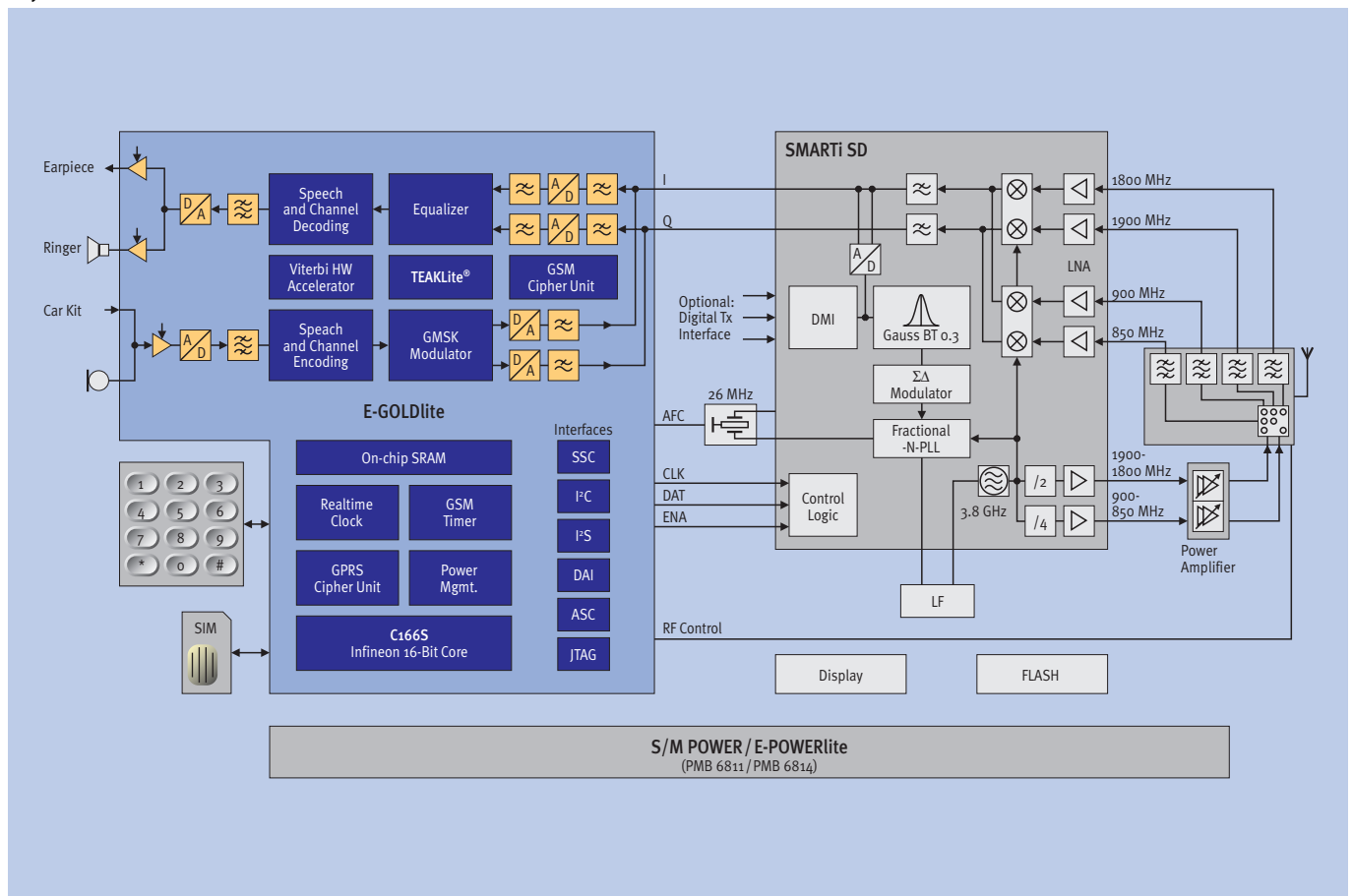
- Product Overview
- Specification
- Mature GPRS protocol stack including Applications from COMNEON
- Complete system designs including PCB, SW and respective services
- User Manual
- Application Note
- Evaluation Board

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Mobile Solutions



## System Architecture with RF-Transceiver SMARTi SD and E-GOLDlite



Note: TEAKLite<sup>®</sup> is a registered trademark of ParthusCeva, Inc.

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Published by  
 Infineon Technologies AG,  
 St.-Martin-Strasse 53,  
 D-81669 München

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Template: pb\_tmplt.fm/4/2004-01-01

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